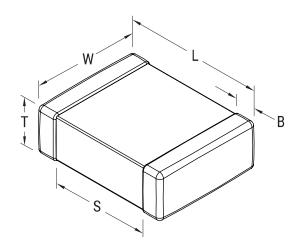


C0603X751G2TAC7411

SMD Comm X8G HT150C Flex, Ceramic, 750 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	4.6 mg	
Shelf Life	78 Weeks	
MSL	1	

100 GOhms

	Specifications	
	Capacitance	750 pF
-0.17mm	Measurement Condition	1 MHz 1.0Vrms
/-0.15mm	Tolerance	2%
/-0.15mm	Voltage DC	200 VDC
lin	Dielectric Withstanding Voltage	500 VDC
+/-0.15mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

 Chip Size
 0603

 L
 1.6mm +/-0.17mm

 W
 0.8mm +/-0.15mm

 T
 0.8mm +/-0.15mm

 S
 0.4mm MIN

 B
 0.45mm +/-0.15mm

Packaging SpecificationsPackagingT&R, 330nPackaging Quantity15000

Dimensions

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.